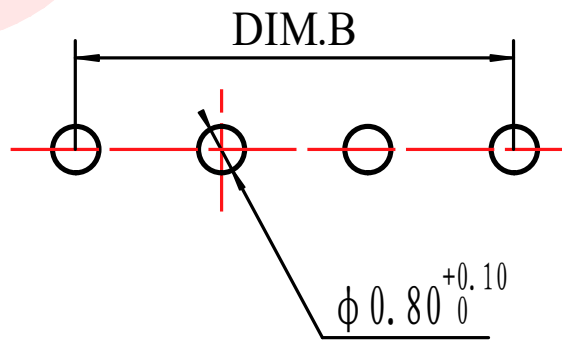
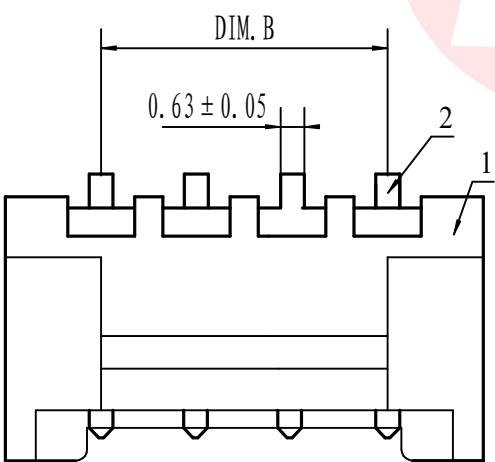
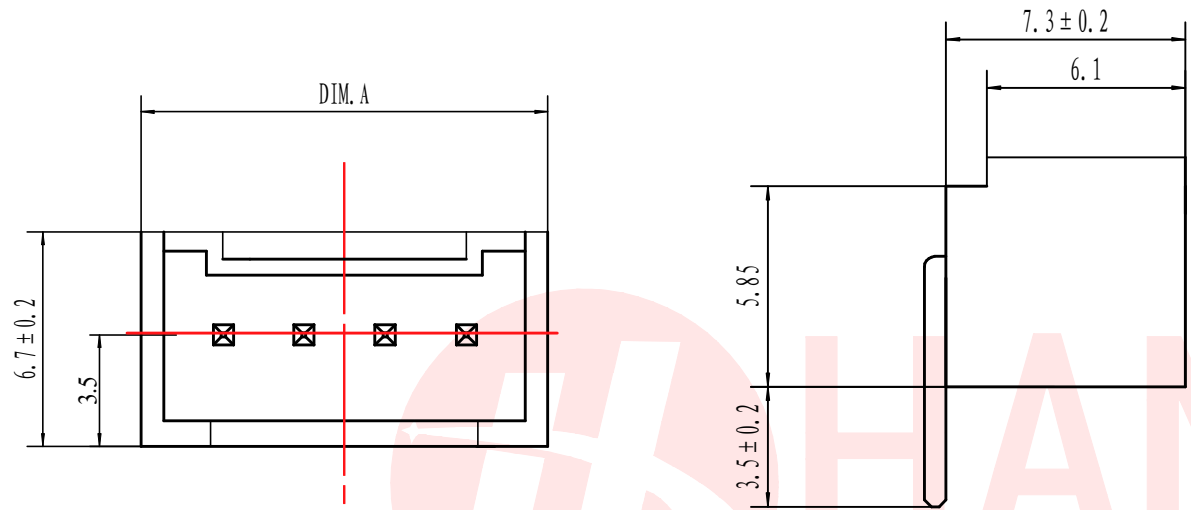




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



PCB LAYOUT

技术要求:

- 1) 材质:见附表;
- 2) 电镀:见附表;
- 3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
- 4) 端子表面无氧化、电镀不良等现象。

适应基板厚度: 1.2mm~1.6mm

温度范围: -25℃~85℃

额定电压: 250V AC/DC

额定电流: 3A

接触电阻: ≤ 0.01Ω

绝缘电阻: ≥ 1000MΩ

耐 压: 1000V AC/minute

TABLE:

CSG PART NO.	PIN#	Dimension mm	
		DIM A	DIM B
WAFER-XHB254WZ-2A	2P	7.50	2.50
WAFER-XHB254WZ-3A	3P	10.00	5.00
WAFER-XHB254WZ-4A	4P	12.50	7.50
WAFER-XHB254WZ-5A	5P	15.00	10.00
WAFER-XHB254WZ-6A	6P	17.50	12.50
WAFER-XHB254WZ-7A	7P	20.00	15.00
WAFER-XHB254WZ-8A	8P	22.50	17.50
WAFER-XHB254WZ-9A	9P	25.00	20.00
WAFER-XHB254WZ-10A	10P	27.50	22.50
WAFER-XHB254WZ-11A	11P	30.00	25.00
WAFER-XHB254WZ-12A	12P	32.50	27.50
WAFER-XHB254WZ-15A	15P	40.00	35.00

2	PIN	n PCS	材质:黄铜,电镀:镀亮锡60u"MIN
1	Housing	1 PCS	材质:PA66 (UL94V-0),颜色:本色/白色/红色
NO.	NAME	Q' TY	DESCRIPTION

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: X :±0.35 X.X :±0.25 X.XX :±0.15

ANGLES: X :±2° X.X :±1°

东莞市汉博电子科技有限公司  
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE: WAFER XHS 2.54立式DIP弯针白色

DWN: xiong PART NO. WAFER-XHB254WZ-NA

CHKD: lee SCALE: 1:1 UNIT: mm

APVD: wang SIZE: A4 SHEET: 10F 1 REV: A4

CUSTOMER COPY